1	2	3	4	5	\bot
				V0 PHORE BRONZE PLATE 1.27 to 2.54 µm Ni CT AREA 0.38 to 0.76 µm Gold R TAIL AREA 2.54 to 5.08 µm Matt Tin	A
12.25 6.70 4.52 90 1.30 2.60 3.50MAX	PIN 6 PIN 10 1.30 2.60 3.35MAX	2.15 3.1 4.9 4.9 5.6 7.4 7.95 10.25 PCB LAYOUT - COMPONENT VIEW	OPERATING TEMPERATURE: COMPLIANCE: RoHS & LEAD	FREE AS PER DIRECTIVE 2002/95/EC EE COMPLIANT AS PER IEC 61249-2-21 ponding ground PIN) 1.8A Max S VOLTAGE: 100Vac/min 100MΩ	В
0.25±0.08 1.30±0.08 2.60±0.08	1.30±0.08 2.60±0.08		MECHANICAL INSERTION FORCE: 35.0N MA EXTRACTION FORCE: 10.0N QUALITY CLASS: 5000 MATIN SOLDERING WAVE & REFLOW PROCESS PACKAGING TAPE & REEL	ax min IG CYCLES	С
RoHS Compliant G F E D		$\bigcirc \qquad \qquad$			-

UNIT: MM

SHEET: 1/2

DRAW: JOE

SCALE:

SIZE

A4

D

DESCRIPTION: MICRO USB 3.0 VERTICAL SMT TYPE B

WERI PART NO: 692 622 030 100

APPROVAL: RJ

GG

JP

ΒY

С

В

Α

REV

26-APR-11

04-AUG-10

DATE

PACKAGING

PDF

FILE